

**TO-252 P Channel Enhancement 沟道增强型
MOS Field Effect Transistor 场效应管**

■ **Features 特点**

Low on-resistance 低导通电阻

$R_{DS(ON)}=12.5m\Omega(\text{Type})@V_{GS}=-10V$

$R_{DS(ON)}=15m\Omega(\text{Type})@V_{GS}=-4.5V$

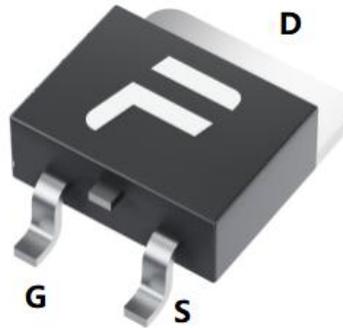
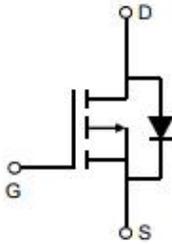
■ **Applications 应用**

Load switch 负载开关

PMW Application 脉宽调制

Power Management 电源管理

■ **Internal Schematic Diagram 内部结构**



■ **Absolute Maximum Ratings 最大额定值**

Characteristic 特性参数	Symbol 符号	Rat 额定值	Unit 单位
Drain-Source Voltage 漏极-源极电压	BV_{DSS}	-60	V
Gate- Source Voltage 栅极-源极电压	V_{GS}	± 20	V
Drain Current (continuous)漏极电流-连续	I_D (at $T_C = 25^\circ C$)	-60	A
Drain Current (pulsed)漏极电流-脉冲	I_{DM}	-240	A
Total Device Dissipation 总耗散功率	$P_D(\text{at } T_C = 25^\circ C)$	73	W
Thermal Resistance Junction-Am 结到环境热阻	$R_{\theta JA}$	62.5	$^\circ C/W$
Thermal Resistance Junction-Case 结壳热阻	$R_{\theta JC}$	1.72	$^\circ C/W$
Avalanche Energy Single Pulse 雪崩能量	E_{AS}	300	mJ
Junction/Storage Temperature 结温/储存温度	T_J, T_{stg}	150, -55~150	$^\circ C$

Electrical Characteristics 电特性

 (T_A=25°C unless otherwise noted 如无特殊说明, 温度为 25°C)

Characteristic 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位
Drain-Source Breakdown Voltage 漏极-源极击穿电压(I _D = -250uA, V _{GS} =0V)	BV _{DSS}	-60	—	—	V
Gate Threshold Voltage 栅极开启电压(I _D = -250uA, V _{GS} = V _{DS})	V _{GS(th)}	-1	-1.8	-2.5	V
Zero Gate Voltage Drain Current 零栅压漏极电流(V _{GS} =0V, V _{DS} = -60V)	I _{DSS}	—	—	-100	nA
Gate Body Leakage 栅极漏电流(V _{GS} =±20V, V _{DS} =0V)	I _{GSS}	—	—	±100	nA
Static Drain-Source On-State Resistance 静态漏源导通电阻(I _D = -20A, V _{GS} = -10V) (I _D = -10A, V _{GS} = -4.5V)	R _{DS(ON)}	—	12.5 15	16 20	mΩ
Diode Forward Voltage Drop 内附二极管正向压降(I _{SD} = -20A, V _{GS} =0V)	V _{SD}	—	—	-1.2	V
Input Capacitance 输入电容 (V _{GS} =0V, V _{DS} = -25V, f=1MHz)	C _{ISS}	—	7067	—	pF
Common Source Output Capacitance 共源输出电容(V _{GS} =0V, V _{DS} = -25V, f=1MHz)	C _{OSS}	—	290	—	pF
Reverse Transfer Capacitance 反馈电容 (V _{GS} =0V, V _{DS} = -25V, f=1MHz)	C _{RSS}	—	252	—	pF
Total Gate Charge 栅极电荷密度 (V _{DS} = -30V, I _D = -20A, V _{GS} = -10V)	Q _g	—	115	—	nC
Gate Source Charge 栅源电荷密度 (V _{DS} = -30V, I _D = -20A, V _{GS} = -10V)	Q _{gs}	—	27	—	nC
Gate Drain Charge 栅漏电荷密度 (V _{DS} = -30V, I _D = -20A, V _{GS} = -10V)	Q _{gd}	—	50	—	nC
Turn-ON Delay Time 开启延迟时间 (V _{DS} = -30V I _D = -20A, R _{GEN} =1 Ω, V _{GS} = -10V)	t _{d(on)}	—	24	—	ns
Turn-ON Rise Time 开启上升时间 (V _{DS} = -30V I _D = -20A, R _{GEN} =1 Ω, V _{GS} = -10V)	t _r	—	18	—	ns
Turn-OFF Delay Time 关断延迟时间 (V _{DS} = -30V I _D = -20A, R _{GEN} =1 Ω, V _{GS} = -10V)	t _{d(off)}	—	56	—	ns
Turn-OFF Fall Time 关断下降时间 (V _{DS} = -30V I _D = -20A, R _{GEN} =1 Ω, V _{GS} = -10V)	t _f	—	30	—	ns

■ Typical Characteristic Curve 典型特性曲线

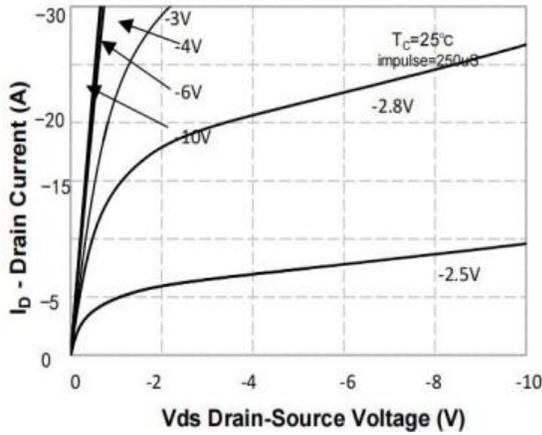


Figure 1: Output Characteristics

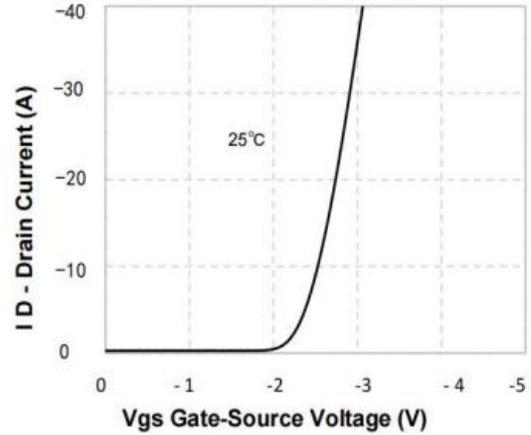


Figure 2: Transfer Characteristics

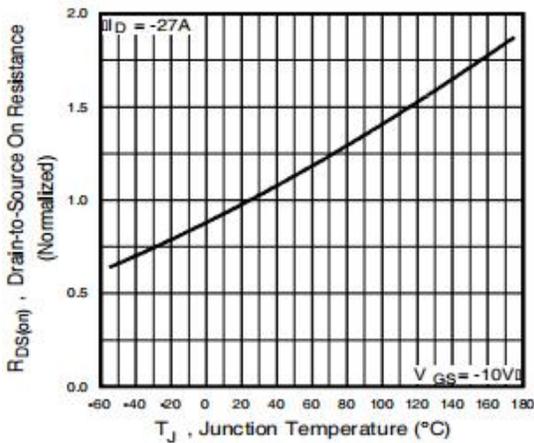


Figure 3: On-Resistance vs. T_j

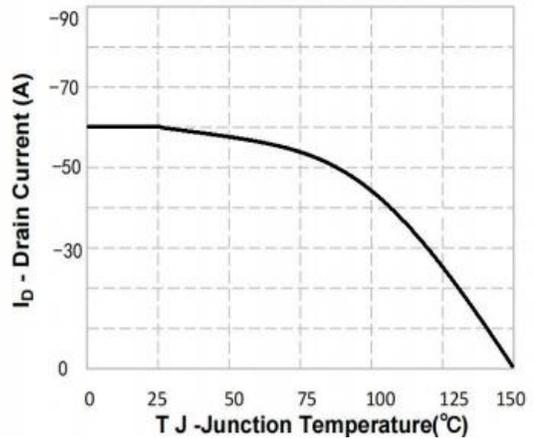


Figure 4: Drain Current vs. T_j

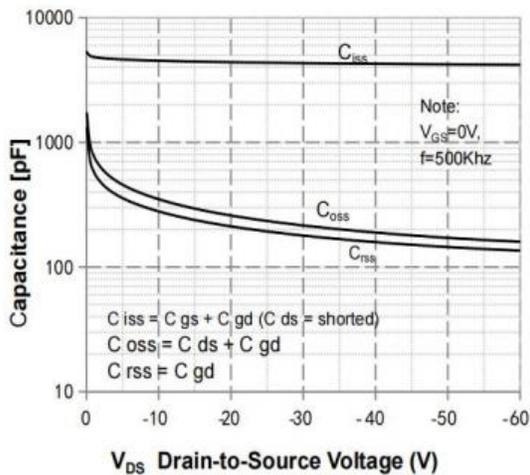


Figure 5: Capacitance Characteristics

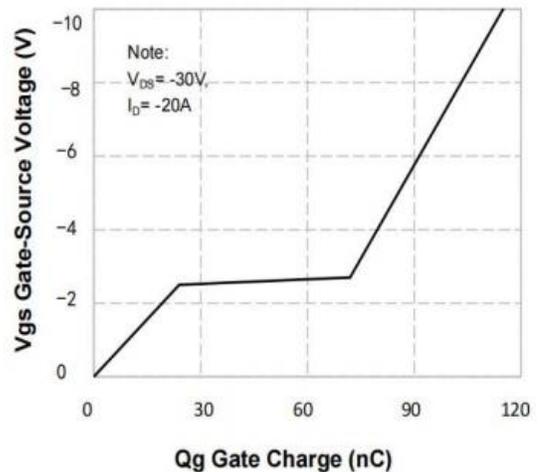


Figure 6: Gate-Charge Characteristics

■ Typical Characteristic Curve 典型特性曲线

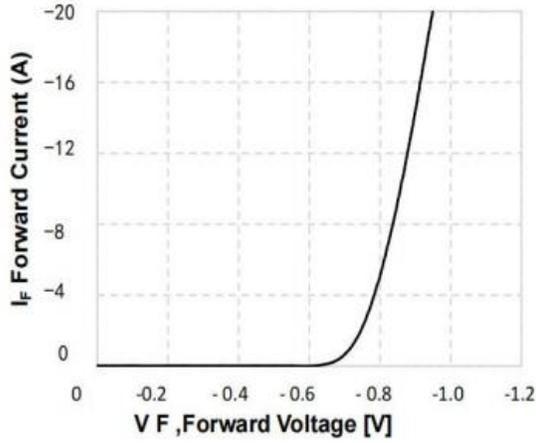


Figure 7: Diode Characteristics

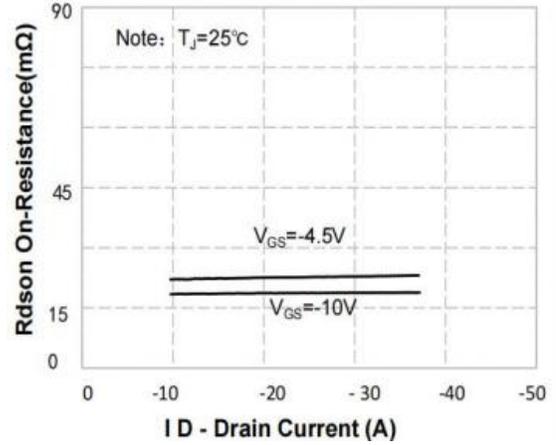


Figure 8: Rdson Id Characteristics

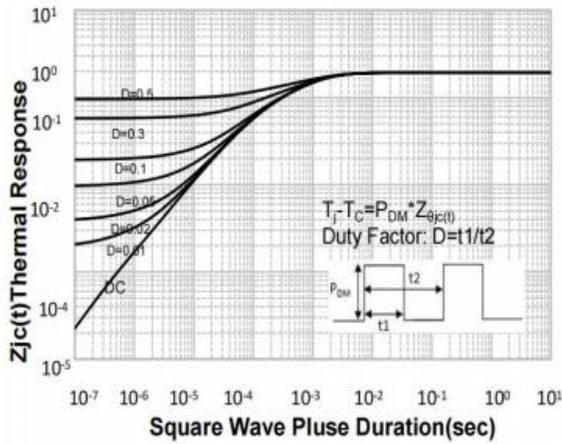


Figure 9: Transient Thermal Response Curve

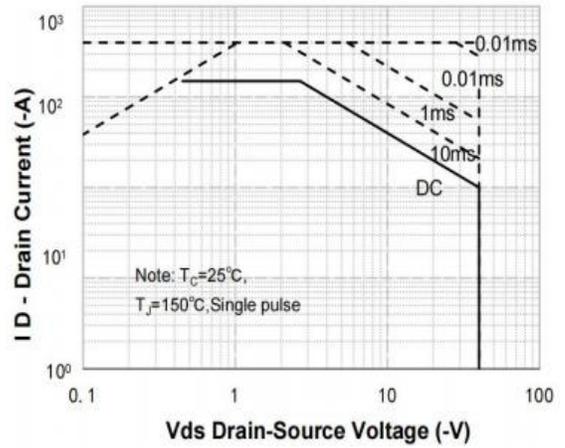
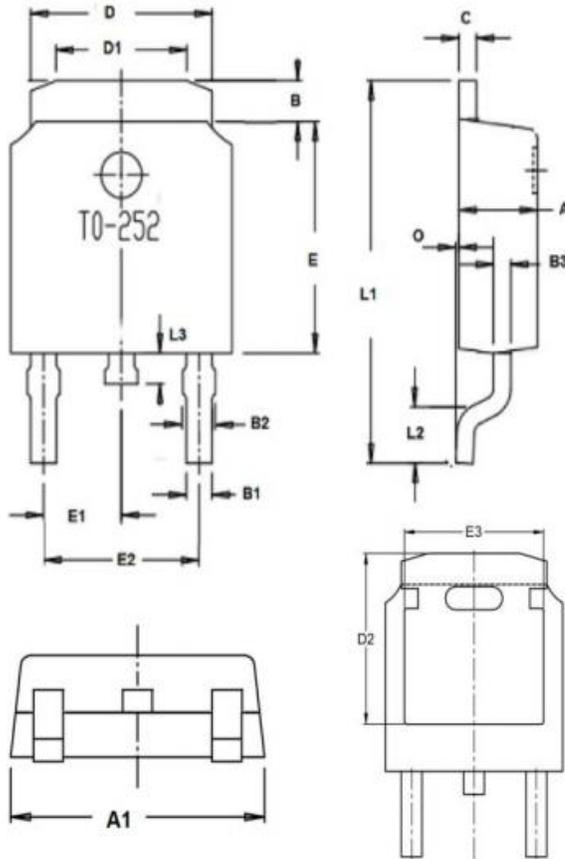


Figure 10: Safe Operating Area

■ Package Dimension 外形封装尺寸



Dim.	Min.	Max.
A	2.1	2.5
A1	6.3	6.9
B	0.96	1.42
B1	0.74	0.86
B2	0.74	0.94
C	Typ0.5	
D	5.33	5.53
D1	3.65	4.05
D2	5	5.4
E	6	6.2
E1	Typ2.29	
E2	Typ4.58	
E3	4.6	5
O	0	0.15
L1	9.9	10.5
L2	Typ1.65	
L3	0.6	1
All Dimensions in millimeter		